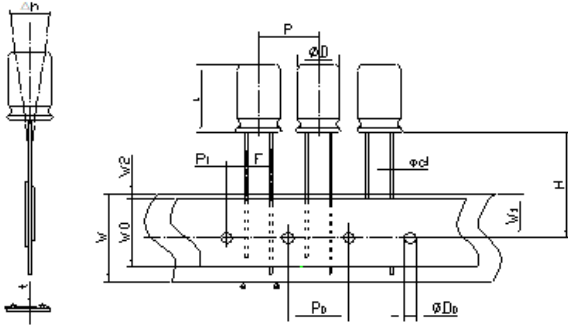


| | | |
|-----------------------------------|---|----------|
| Huawei P/N: LD2G6R8MG125B50CE0 | CHANGZHOU HUAWEI ELECTRONICS CO.,LTD LD 400V 6.80 μ F 10*12.5 | Page:1/1 |
|-----------------------------------|---|----------|

Customer : Ropla Elektronik Sp. z o.o.
Customer P/N :

Diagram Of Dimensions




unit: mm



| | | | |
|------------|------|--------|------|
| D | 10 | L | 12.5 |
| βMax | +0.5 | αMax | +1.5 |
| d±0.05 | 0.6 | P±1.0 | 12.7 |
| P0±0.2 | 12.7 | P1±0.5 | 3.85 |
| F+0.3/-0.2 | 5.0 | W±0.5 | 18.0 |
| W1±0.5 | 9.0 | W2 | ≤1.5 |
| W0 | ≥12 | H±0.75 | 18.5 |
| D0±0.2 | 4.00 | t±0.2 | 0.7 |
| Δh | ≤2.0 | | |

β 为 D 值公差 / α 为 L 值公差

| Items | Performance | | | | | |
|---|--|---|------|------|------|------|
| Operating Temperature Range | -40°C ~ +105°C | | | | | |
| Capacitance Tolerance | -20% ~ +20% (120Hz,20°C) | | | | | |
| Surge Voltage | 450VDC | | | | | |
| Leakage Current | LC≤64.4μA After 2 minutes | | | | | |
| Dissipation Factor (Tan δ) | ≤0.20 (120Hz,20°C) | | | | | |
| ESR | 9.5 Ω (100KHz, 25°C) | | | | | |
| Ripple Currents | 120mA (100KHz, +105°C) | | | | | |
| Low Temperature Characteristics(120Hz) | Z-40°C / Z+20°C | | | 7 | | |
| Ripple Current & Frequency Multipliers | Frequency(Hz) | 120 | 50 | 10K | 1K | 100K |
| | Coefficient | 0.50 | 0.40 | 0.90 | 0.80 | 1.00 |
| Life Test: Load Life Test: After 8000 Hrs at 105°C Shelf Life Test: After 1000 Hrs at 105°C | Capacitance Change | Load Life: Within ±20% of initial value | | | | |
| | | Shelf Life: Within ±20% of initial value | | | | |
| | Dissipation Factor | Load Life: Less than 200% of specified value | | | | |
| | | Shelf Life: Less than 200% of specified value | | | | |
| Leakage current | Load Life: Within specified value | | | | | |
| | Shelf Life: Less than 200% of specified value | | | | | |
| Solder ability | 245 ± 5°C, 2 ± 0.5 seconds. soldering must cover more than 95% | | | | | |
| Standards | IEC-60384 | | | | | |
| Remarks | RoHS Compliance & Halogen-Free | | | | | |

| | | | | | |
|--------------|-------------|----------------------|--|--|---|
| Publish Date | 18-Oct-2024 | Approval Signatures: | Approved | Checked | Designed |
| Revise Date | | |  詹光耀 研发中心 |  魏丽芳 研发中心 |  钱卢苏蒙 研发中心 |
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